DuPon™ CuSolve™
Copper Compatible Removers
Optimized to Selectively Remove Post-Etch Residues

Product Description
DuPont™ CuSolve™ copper compatible removers are designed to remove post-etch residue. They perform well in a variety of equipment including single-wafer and batch spray platforms.

Features
• Formulated for optimum compatibility with copper substrates
• Compatible with single-wafer type clean equipment
• Compatible with batch spray type clean equipment
• Aqueous-based formulation
• No post-clean rinse required other than water
• Operates well below the flashpoint of the solution
• Low evaporation rate at operating temperature
• Low viscosity
• High flashpoint
• No banned or reportable chemical components
• Copper oxide removal time <30 seconds at 25 °C
• Compatible with a variety of Low-k films
• Bathlife >48 hours
• Lower cost of ownership than competitive products

Benefits
• Improved yields in copper processing
• Offers flexibility in equipment choice
• Greater device reliability and product yields
• Helps reduce environmental, health and safety concerns
• Provides a safer chemical process
• Long bath life, low air emissions, low factory operating cost
• Ease of operation of tool and chemical supply equipment

Figure 1. Before Clean

Figure 2. After Clean with DuPont™ CuSolve™
Copper Compatible Remover
Figure 3. Materials Compatibility (total loss in 10 minutes at 25 °C)

Substrates were exposed to DuPont™ CuSolve™ EKCS20™ at 25 °C for 10 minutes. Etch rates were calculated.